## Nch 650V 20A Power MOSFET

$V_{DSS}$	650V
R <sub>DS(on)</sub> (Max.)	0.205Ω
I <sub>D</sub>	±20A
$P_D$	231W

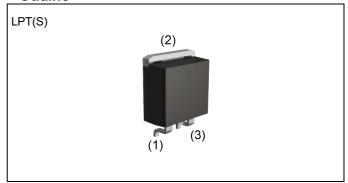
# ● Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

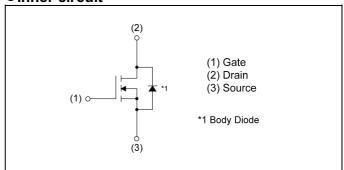
## Application

Switching

## Outline



## •Inner circuit



Packaging specifications

or ackaging specifications	
Packing	Embossed Tape
Packing code	TL
Marking	R6520ENJ
Basic ordering unit (pcs)	1000

## ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	650	V
Continuous drain current (T <sub>c</sub> = 25°C)		I <sub>D</sub> *1	±20	Α
Pulsed drain current	I <sub>DP</sub> *2	±60	Α	
Gate - Source voltage static AC(f>1Hz)		V	±20	V
		V <sub>GSS</sub>	±30	V
Avalanche current, single pulse	·	I <sub>AS</sub>	3.4	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	444	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	231	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tempera	ature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Dougrantou	Currele e l	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	0.54	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Davameter	Cymah al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	650	-	-	V
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ
		$T_j = 125^{\circ}C$	ı	-	1000	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 630 \mu A$	2	-	4	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 9.5A				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.185	0.205	Ω
		$T_j = 125^{\circ}C$	-	-	-	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	6	-	Ω

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darramatar	Cymah al	Conditions		Unit			
Parameter	Symbol	Symbol Conditions –		Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1400	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	1500	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	150	1		
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	30	-		
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 10A	-	50	-		
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L \simeq 30\Omega$	-	155	-	ns	
Fall time	t <sub>f</sub> *6	$R_G = 10\Omega$	-	60	-		

## ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah ol	Conditions	Values			l linit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Total gate charge	Q <sub>g</sub> *6	V <sub>DD</sub> ≈ 300V	-	61	-		
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 20A	-	8.5	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *6	V <sub>GS</sub> = 10V	-	32	-		
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 20A	-	5.9	-	V	

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 70mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

<sup>\*6</sup> Pulsed

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Unit			
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I <sub>S</sub> *1	· T <sub>C</sub> = 25°C	1	-	20	Α	
Pulsed source current	l <sub>SP</sub> *2	1C - 23 C	1	-	60	Α	
Source-Drain voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *6		-	500	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 20A di/dt = 100A/μs	-	8	-	μC	
Peak reverse recovery current	<sub>rr</sub> *6		-	32	-	А	

Fig.1 Power Dissipation Derating Curve

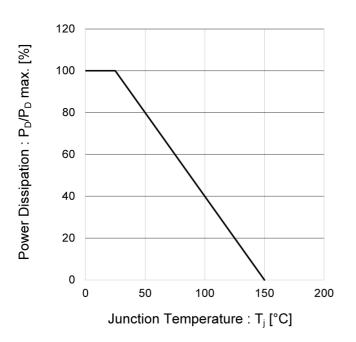


Fig.2 Drain Current Derating Curve

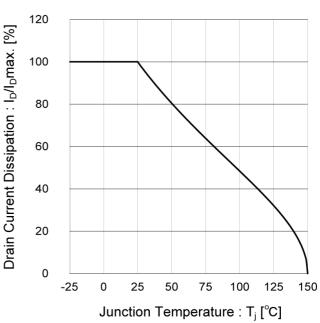


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

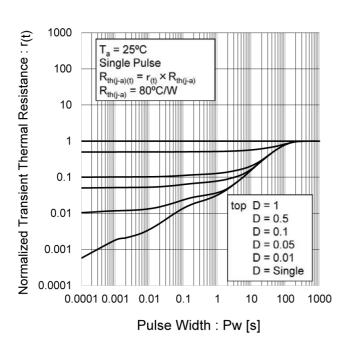


Fig.4 Maximum Safe Operating Area

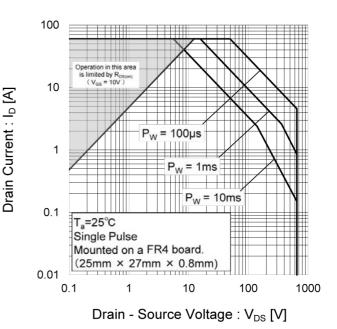


Fig.5 Avalanche Energy Derating Curve

120 Avalanche Energy: EAS / EAS max [%] 100 80 60 40 20 0 0 25 50 75 100 125 175 Junction Temperature : T<sub>j</sub> [°C]

Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

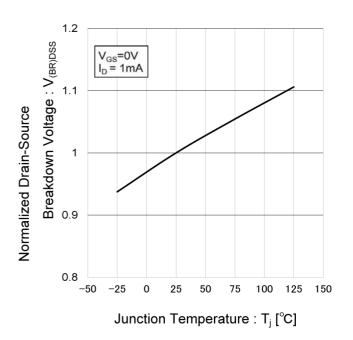


Fig.7 Typical Output Characteristics(I)

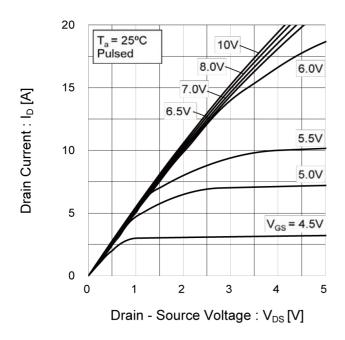
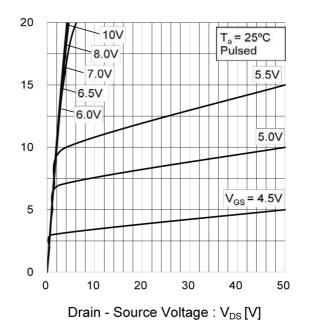


Fig.8 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

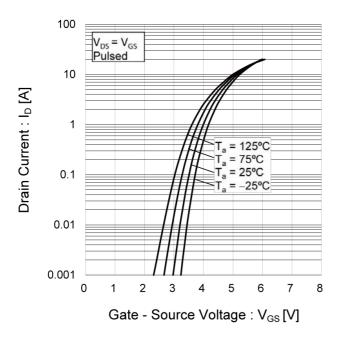


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

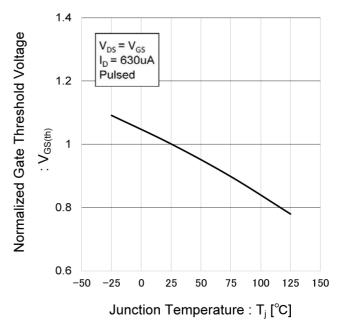


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

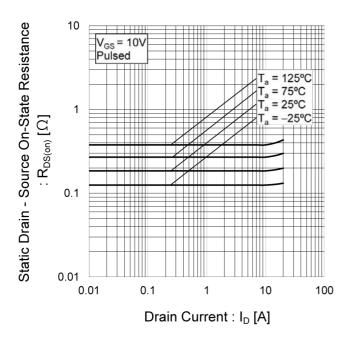


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

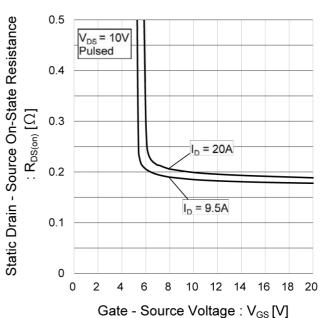


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

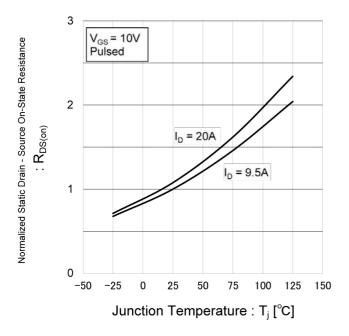


Fig.14 Typical Capacitance vs.

Drain - Source Voltage

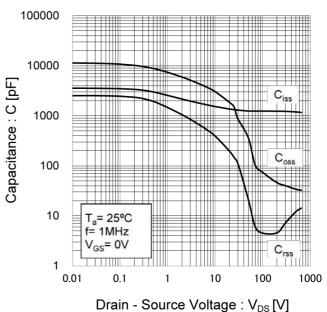


Fig.15 Switching Characteristics

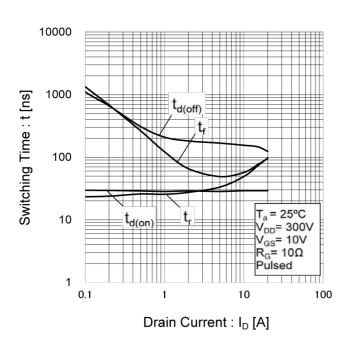
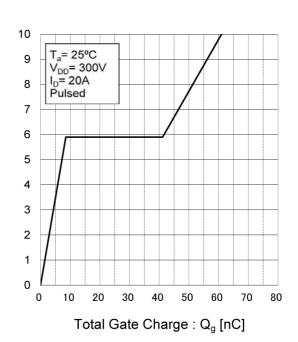


Fig.16 Typical Gate Charge



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage

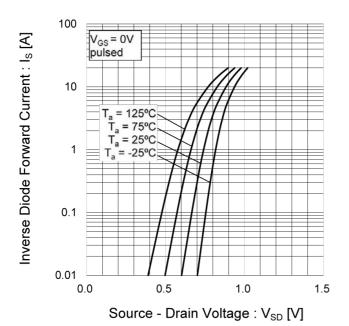
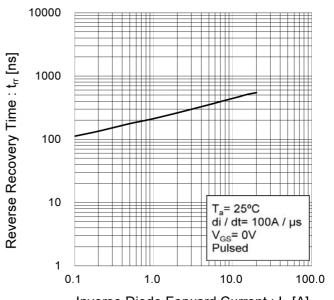


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current :  $I_S$  [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

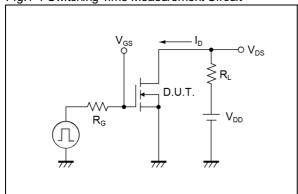


Fig.2-1 Gate Charge Measurement Circuit

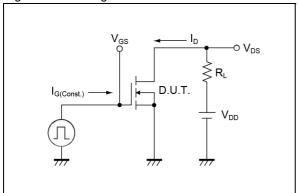


Fig.3-1 Avalanche Measurement Circuit

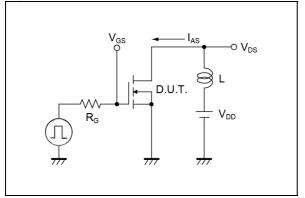


Fig.4-1 trr Measurement Circuit

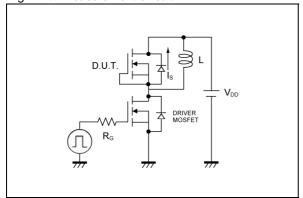


Fig.1-2 Switching Waveforms

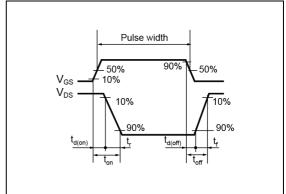


Fig.2-2 Gate Charge Waveform

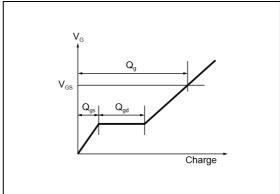


Fig.3-2 Avalanche Waveform

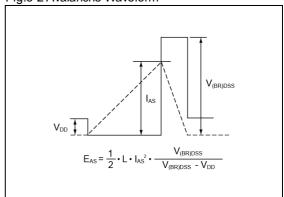
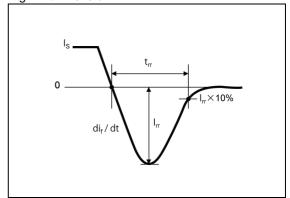
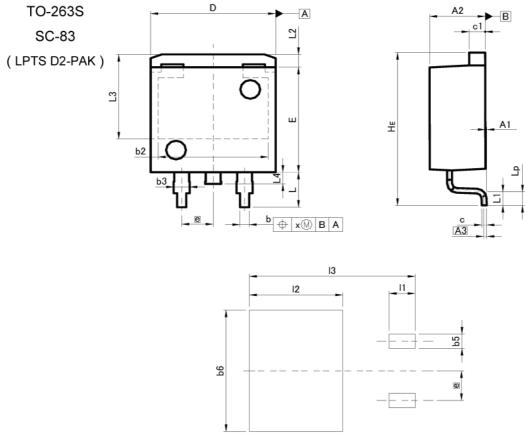


Fig.4-2 trr Waveform



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:		0.0	
b	0.68	0.98	0.027	0.039
b2	8.9			50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	20	0.047	
L2	1.	10	0.043	
L3	7.:	7.25		85
L4	1,0	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	770	0.25	-	0.010
	MILIMA		INC	1150

DIM	MILIMETERS		MILIMETERS INC	
DIM	MIN	MAX	MIN	MAX
bb	=:	1.23	-	0.049
b6	<b>=</b> 0	10.40	<del></del>	0.409
11	23	2.10		0.083
12	<del>77</del> .4	7.55	1.00	0.297
13	-	13.40	3 <del></del>	0.528

Dimension in mm/inches



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CLASSⅢ	CLASSIII	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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